

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
- Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.



April 1988 Revised October 2000

74F573

Octal D-Type Latch with 3-STATE Outputs

General Description

The 74F573 is a high speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable (\overline{OE}) inputs.

This device is functionally identical to the 74F373 but has different pinouts.

Features

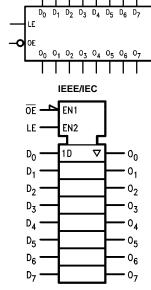
- Inputs and outputs on opposite sides of package allowing easy interface with microprocessors
- Useful as input or output port for microprocessors
- Functionally identical to 74F373
- 3-STATE outputs for bus interfacing
- Guaranteed 4000V minimum ESD protection

Ordering Code:

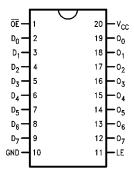
Order Number	Package Number	Package Description
74F573SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F573SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F573PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbols



Connection Diagram



Unit Loading/Fan Out

Pin Names	December 1	U.L.	Input I _{IH} /I _{IL}	
	Description	HIGH/LOW	Output I _{OH} /I _{OL}	
D ₀ –D ₇	Data Inputs	1.0/1.0	20 μA/-0.6 mA	
LE	Latch Enable Input (Active HIGH)	1.0/1.0	20 μA/-0.6 mA	
OE	3-STATE Output Enable Input (Active LOW)	1.0/1.0	20 μA/–0.6 mA	
O ₀ -O ₇	3-STATE Latch Outputs	150/40(33.3)	-3 mA/24 mA (20 mA)	

Functional Description

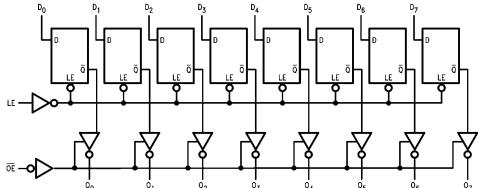
The 74F573 contains eight D-type latches with 3-state output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-state buffers are controlled by the Output Enable (\overline{OE}) input. When \overline{OE} is LOW, the buffers are in the bi-state mode. When \overline{OE} is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

Function Table

	Outputs		
OE	LE	D	0
L	Н	Н	Н
L	Н	L	L
L	L	X	O ₀
Н	X	X	Z

H = HIGH Voltage Level

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

L = LOW Voltage Level

X = Immaterial

O₀ = Value stored from previous clock cycle

Absolute Maximum Ratings(Note 1)

 $\begin{array}{ll} \mbox{Storage Temperature} & -65\mbox{°C to } +150\mbox{°C} \\ \mbox{Ambient Temperature under Bias} & -55\mbox{°C to } +125\mbox{°C} \\ \end{array}$

 $\begin{array}{lll} \mbox{Junction Temperature under Bias} & -55^{\circ}\mbox{C to } +150^{\circ}\mbox{C} \\ \mbox{V}_{\mbox{CC}} \mbox{ Pin Potential to Ground Pin} & -0.5\mbox{V to } +7.0\mbox{V} \end{array}$

Voltage Applied to Output

in HIGH State (with $V_{CC} = 0V$)

 $\begin{array}{ll} \text{Standard Output} & -0.5 \text{V to V}_{\text{CC}} \\ \text{3-STATE Output} & -0.5 \text{V to +5.5 V} \end{array}$

Current Applied to Output

in LOW State (Max) twice the rated I_{OL} (mA) ESD Last Passing Voltage (Min) 4000V

Recommended Operating Conditions

Free Air Ambient Temperature 0°C to +70°C Supply Voltage +4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

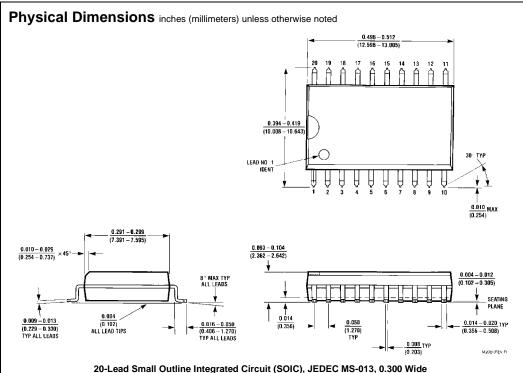
Symbol	Parameter		Min	Тур	Max	Units	v _{cc}	Conditions	
V _{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal	
V _{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal	
V _{CD}	Input Clamp Diode Voltage				-1.2	V	Min	I _{IN} = -18 mA	
V _{OH}	Output HIGH	10% V _{CC}	2.5					I _{OH} = -1 mA	
	Voltage	10% V _{CC}	2.4			V	Min	$I_{OH} = -3 \text{ mA}$	
		$5\% V_{CC}$	2.7			V	IVIIII	$I_{OH} = -1 \text{ mA}$	
		$5\% V_{CC}$	2.7					$I_{OH} = -3 \text{ mA}$	
V _{OL}	Output LOW	10% V _{CC}			0.5	V	Min	I _{OI} = 24 mA	
	Voltage				0.5	V	IVIIII	10L = 24 IIIA	
I _{IH}	Input HIGH				20.0	μА	Max	V _{IN} = 2.7V	
	Current				5.0	μΑ	IVIAX	v _{IN} = 2.7 v	
I _{BVI}	Input HIGH Current				7.0	μА	Max	V _{IN} = 7.0V	
	Breakdown Test				7.0	μΑ	IVIAX	V _{IN} = 7.0V	
I _{CEX}	Output HIGH				50	μА	Max	V _{OUT} = V _{CC}	
	Leakage Current				30	μΑ IVIAX		VOUT - VCC	
V _{ID}	Input Leakage		4.75			V	0.0	$I_{ID} = 1.9 \mu A$	
	Test		4.75			V	0.0	All Other Pins Grounded	
I _{OD}	Output Leakage				3.75	μА	0.0	V _{IOD} = 150 mV	
	Circuit Current				3.73	μΑ	0.0	All Other Pins Grounded	
I _{IL}	Input LOW Current				-0.6	mA	Max	$V_{IN} = 0.5V$	
I _{OZH}	Output Leakage Current				50	μΑ	Max	V _{OUT} = 2.7V	
I _{OZL}	Output Leakage Current				-50	μΑ	Max	V _{OUT} = 0.5V	
Ios	Output Short-Circuit Current		-60		-150	mA	Max	V _{OUT} = 0V	
I _{ZZ}	Bus Drainage Test				500	μΑ	0.0V	V _{OUT} = 5.25V	
I _{CCL}	Power Supply Current			35	55	mA	Max	$V_O = LOW$	
I _{CCZ}	Power Supply Current			35	55	mA	Max	V _O = HIGH Z	

AC Electrical Characteristics

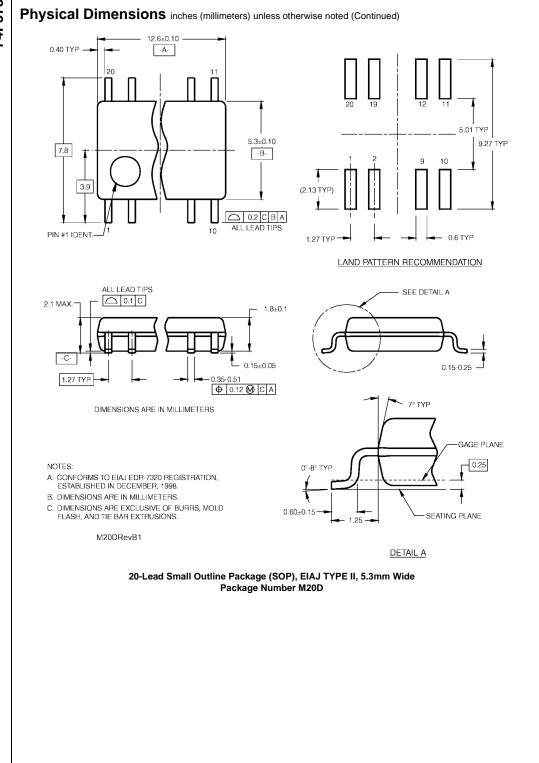
	Parameter	$T_A = +25^{\circ}C$ $V_{CC} = +5.0V$ $C_L = 50 \text{ pF}$			$T_{A} = -55^{\circ}C \text{ to } +125^{\circ}C$ $V_{CC} = +5.0V$ $C_{L} = 50 \text{ pF}$		$T_A = 0$ °C to +70°C $V_{CC} = +5.0V$ $C_L = 50$ pF		Units
Symbol									
		t _{PLH}	Propagation Delay	3.0	5.3	7.0	3.0	9.0	3.0
t _{PHL}	D _n to O _n	2.0	3.7	6.0	2.0	7.0	2.0	6.5	
t _{PLH}	Propagation Delay	5.0	9.0	11.0	5.0	13.5	5.0	12.0	20
t_{PHL}	LE to O _n	3.0	5.2	7.0	3.0	7.5	3.0	7.0	ns
t _{PZH}	Output Enable Time	2.0	5.0	8.0	2.0	10.0	2.0	9.0	
t_{PZL}		2.0	5.6	8.5	2.0	10.0	2.0	9.5	ns
t _{PHZ}	Output Disable Time	1.5	4.5	5.5	1.5	7.0	1.5	6.5	115
t_{PLZ}		1.5	3.8	5.5	1.5	5.5	1.5	5.5	

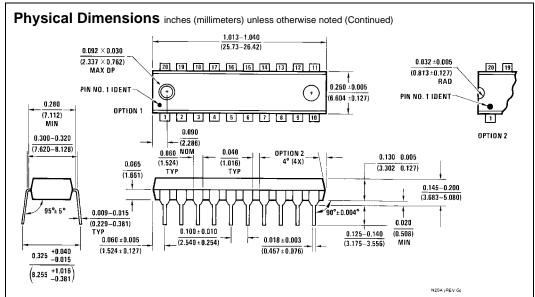
AC Operating Requirements

Symbol	Parameter	$T_A = +25^{\circ}C$ $V_{CC} = +5.0V$		$T_A = -55^{\circ}C$ to $+125^{\circ}C$ $V_{CC} = +5.0V$		$T_A = 0$ °C to +70°C $V_{CC} = +5.0V$		Units
		Min	Max	Min	Max	Min	Max	
t _S (H)	Setup Time, HIGH or LOW	2.0		2.0		2.0		
$t_S(L)$	D _n to LE	2.0		2.0		2.0		20
t _H (H)	Hold Time, HIGH or LOW	3.0		3.0		3.0		ns
t _H (L)	D _n to LE	3.5		4.0		3.5		
t _W (H)	LE Pulse Width, HIGH	4.0		4.0		4.0		ns



20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide Package Number M20B





20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N20A

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com